

January 2002 Revised September 2002

# **FIN1101**

# **LVDS Single Port High Speed Repeater**

## **General Description**

This single port repeater is designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. It accepts and outputs LVDS levels with a typical differential output swing of 330 mV which provides low EMI at ultra low power dissipation even at high frequencies. It can directly accept multiple differential I/O including: LVPECL, HSTL, and SSTL-2 for translating directly to LVDS.

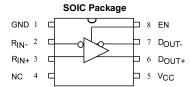
### **Features**

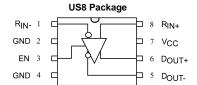
- Up to 1.6 Gb/s full differential path
- 3.5 ps max random jitter and 135 ps max deterministic iitter
- 3.3V power supply operation
- Wide rail-to-rail common mode range
- Ultra low power consumption
- LVDS receiver inputs accept LVPECL, HSTL, and SSTL-2 directly
- Power off protection
- 7 kV HBM ESD protection (all pins)
- Meets or exceed the TA/EIA-644-A LVDS standard
- Packaged in 8-pin SOIC and US8
- Open circuit fail safe protection

# **Ordering Code:**

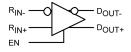
Order Number	Package Number	Package Description
FIN1101M	M08A	8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TUBE]
FIN1101MX		8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow [TAPE and REEL]
FIN1101K8X		8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide [TAPE and REEL]

## **Connection Diagrams**





### **Functional Diagram**



# **Pin Descriptions**

Pin Name	Description			
R <sub>IN+</sub>	Non-Inverting LVDS Inputs			
R <sub>IN-</sub>	Inverting LVDS Inputs			
D <sub>OUT+</sub>	Non-Inverting Driver Outputs			
D <sub>OUT</sub>	Inverting Driver Outputs			
EN	Driver Enable Pin			
V <sub>CC</sub>	Power Supply			
GND	Ground			

### **Function Table**

	Inputs	Outputs			
EN R <sub>IN+</sub>		R <sub>IN</sub>	D <sub>OUT+</sub>	D <sub>OUT</sub>	
Н	Н	L	Н	L	
Н	L	Н	L	Н	
Н	Fail Saf	e Case	Н	L	
L	Х	Χ	Z	Z	

H = HIGH Logic Level

L = LOW Logic Level Z = High Impedance

# **Absolute Maximum Ratings**(Note 1)

 $\label{eq:total_stress} Storage\ Temperature\ Range\ (T_{STG}) \qquad -65^{\circ}C\ to\ +150^{\circ}C$  Max Junction Temperature (T\_J)  $\qquad \qquad 150^{\circ}C$ 

Lead Temperature (T<sub>L</sub>)

(Soldering, 10 seconds) 260°C ESD (Human Body Model) 7000V ESD (Machine Model) 300V

# Recommended Operating Conditions

Supply Voltage (V<sub>CC</sub>) 3.0V to 3.6V Operating Temperature (T<sub>A</sub>)  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ 

Magnitude of Input

Differential Voltage ( $|V_{ID}|$ ) 100 mV to  $V_{CC}$ 

150°C Common Mode Input Voltage

 $(V_{IC})$   $(0V + |V_{ID}|/2)$  to  $(V_{CC} - |V_{ID}|/2)$ 

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

### **DC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions		Min	(Note 2)	мах	Units
V <sub>TH</sub>	Differential Input Threshold HIGH	See Figure 1; $V_{IC} = +0.05V$ , $+1.2V$ , or $(V_{CC} - 0.05V)$				100	mV
V <sub>TL</sub>	Differential Input Threshold LOW	See Figure 1; $V_{IC} = +0.05V$ , $+1.2V$ , or $(V_{CC})$	- 0.05V)	-100			mV
V <sub>IH</sub>	Input High Voltage (EN)			2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Input Low Voltage (EN)			GND		0.8	V
V <sub>OD</sub>	Output Differential Voltage			250	330	450	mV
$\Delta V_{OD}$	V <sub>OD</sub> Magnitude Change from Differential LOW-to-HIGH	$R_L = 100 \Omega$ , Driver Enabled, See Figure 2				25	mV
Vos	Offset Voltage			1.125	1.23	1.375	V
ΔV <sub>OS</sub>	Offset Magnitude Change from Differential LOW-to-HIGH					25	mV
Ios	Short Circuit Output Current	D <sub>OUT+</sub> = 0V & D <sub>OUT-</sub> = 0V, Driver Enabled			-3.4	-6	mA
		V <sub>OD</sub> = 0V, Driver Enabled			±3.4	±6	mA
I <sub>IN</sub>	Input Current (EN, D <sub>INX+</sub> , D <sub>INX</sub> -)	$V_{IN} = 0V$ to $V_{CC}$ , Other Input = $V_{CC}$ or 0V (for Differential Inputs)				±20	μА
I <sub>OFF</sub>	Power-Off Input or Output Current	$V_{CC} = 0V$ , $V_{IN}$ or $V_{OUT} = 0V$ to 3.6V				±20	μΑ
I <sub>CCZ</sub>	Disabled Power Supply Current	Drivers Disabled			3.2	5.5	mA
Icc	Power Supply Current	Drivers Enabled, Any Valid Input Condition			9.3	13.5	mA
I <sub>OZ</sub>	Disabled Output Leakage Current	Driver Disabled, D <sub>OUT+</sub> = 0V to 3.6V or D <sub>OUT-</sub> = 0V to 3.6V				±20	μА
V <sub>IC</sub>	Common Mode Voltage Range	V <sub>ID</sub>   = 100 mV to V <sub>CC</sub>		$0V +  V_{ID }/2$		V <sub>CC</sub> - ( V <sub>ID</sub>  /2)	V
C <sub>IN</sub>	Input Capacitance	E	N Input		2.2		pF
		D	ata Input		2.0		۲۰
C <sub>OUT</sub>	Output Capacitance				2.6		pF

**Note 2:** All typical values are at  $T_A = 25^{\circ}C$  and with  $V_{CC} = 3.3V$ .

## **AC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

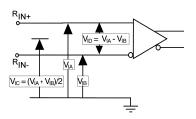
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
				(Note 3)		
t <sub>PLHD</sub>	Differential Propagation Delay		0.75	1.1	1.75	ns
	LOW-to-HIGH		0.75	1.1	1.75	115
t <sub>PHLD</sub>	Differential Propagation Delay	$R_L = 100 \Omega, C_L = 5 pF,$	0.75	1.1	1.75	ns
	HIGH-to-LOW	$V_{ID} = 200 \text{ mV to } 450 \text{ mV},$	0.75	1.1	1.75	115
t <sub>TLHD</sub>	Differential Output Rise Time (20% to 80%)	$V_{IC} =  V_{ID} /2 \text{ to } (V_{CC-} (V_{ID}/2),$	0.29	0.40	0.58	ns
t <sub>THLD</sub>	Differential Output Fall Time (80% to 20%)	Duty Cycle = 50%,	0.29	0.40	0.58	ns
t <sub>SK(P)</sub>	Pulse Skew  t <sub>PLH</sub> - t <sub>PHL</sub>	See Figure 3 and Figure 4		0.01	0.2	ns
t <sub>SK(PP)</sub>	Part-to-Part Skew (Note 4)				0.5	ns
f <sub>MAX</sub>	Maximum Frequency (Note 5)(Note 6)		400	800		MHz
t <sub>PZHD</sub>	Differential Output Enable Time from Z to HIGH			2.1	5	ns
t <sub>PZLD</sub>	Differential Output Enable Time from Z to LOW	$R_L = 100 \Omega, C_L = 5 pF,$		2.3	5	ns
t <sub>PHZD</sub>	Differential Output Disable Time from HIGH to Z	See Figure 2 and Figure 3		1.5	5	ns
t <sub>PLZD</sub>	Differential Output Disable Time from LOW to Z			1.8	5	ns
t <sub>DJ</sub>	LVDS Data Jitter,	$V_{ID} = 300 \text{ mV}, PRBS = 2^{23} - 1,$		85	135	ps
	Deterministic	V <sub>IC</sub> = 1.2V at 800 Mbps		0.5		
t <sub>RJ</sub>	LVDS Clock Jitter, Random	V <sub>ID</sub> = 300 mV		2.1	3.5	ps
	(RMS)	V <sub>IC</sub> = 1.2 V at 400 MHz		2.1	5.5	μs

Note 3: All typical values are at  $T_A = 25$ °C and with  $V_{CC} = 3.3$ V,  $V_{ID} = 300$ mV,  $V_{IC} = 1.2$ V unless otherwise specified.

Note 4: t<sub>SK(PP)</sub> is the magnitude of the difference in differential propagation delay times between identical channels of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

Note 5: Passing criteria for maximum frequency is the output V<sub>OD</sub> > 200 mV and the duty cycle is 45% to 55% with all channels switching.

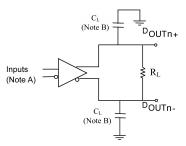
 $\textbf{Note 6:} \ \text{Output loading is transmission line environment only; } \ C_L \ \text{is} < 1 \ \text{pF of stray test fixture capacitance.}$ 



HIGH or LOW R<sub>L</sub>/2 V<sub>OD</sub>

FIGURE 1. Differential Receiver Voltage Definitions and Propagation I and Transition Time Test Circuit

FIGURE 2. Differential Driver DC Test Circuit



Note A: All LVDS input pulses have frequency = 10MHz,  $t_R$  or  $t_F$  <= 0.5 ns Note B:  $C_L$  includes all probe and test fixture capacitances

FIGURE 3. Differential Driver Propagation Delay and Transition Time Test Circuit

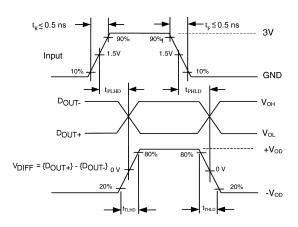
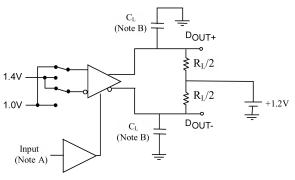


FIGURE 4. AC Waveforms



Note A: All LVTTL input pulses have frequency = 10 MHz,  $t_R$  or  $t_F$  < = 2 ns Note B:  $C_L$  includes all probe and test fixture capacitances

FIGURE 5. Differential Driver Enable and Disable Test Circuit

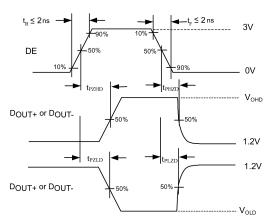
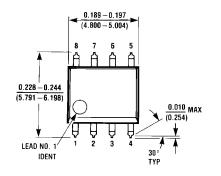
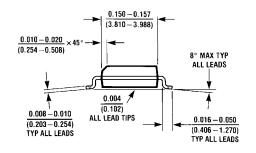
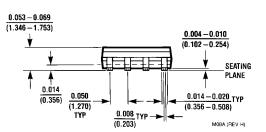


FIGURE 6. Enable and Disable AC Waveforms

# Physical Dimensions inches (millimeters) unless otherwise noted

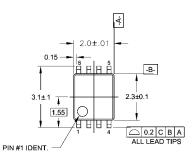


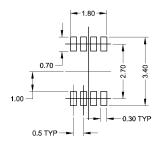




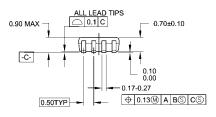
8-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M08A

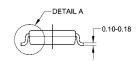
## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

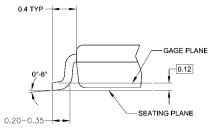




### LAND PATTERN RECOMMENDATION







### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187 B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

DETAIL A

#### MAB08AREVC

# 8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide Package Number MAB08A

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